

银/钯导电浆料说明书

Silver Palladium Conductor Ink Datasheet

P/N: DHC-PF-8083D

改定编号: 1 改定日期: 2006.06.30

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1. 适用范围

1.Scope of application

此说明适用于由上海大洲生产的 **DHC-PF-8083D**，用于 **HIC** 和电阻生产银钯导电浆料，**DHC-PF-8083D** 具有强附着力，可焊性好，耐焊性好和低电阻率，主要成分为银粉，钯粉，玻璃粉，有机粘接剂，溶剂和添加剂。

This specification apply to **DHC-PF-8083D** produced by Shanghai Dazhou,used for production of **HIC** and resistance, by meaning of silver palladium ink. **DHC-PF-8083D** has strong adhesion, good solderability, fine soldering resistance and low resistivity. The main element are silver powder, palladium powder, glass powder, organic adhesive, solvent and additive.

2.使用方法

2.Method of application

2-1. 印刷方法：丝网印刷（标准：325，250Mesh）

2-1. Printing methods: screen printing (standard: 325,250 Mesh)

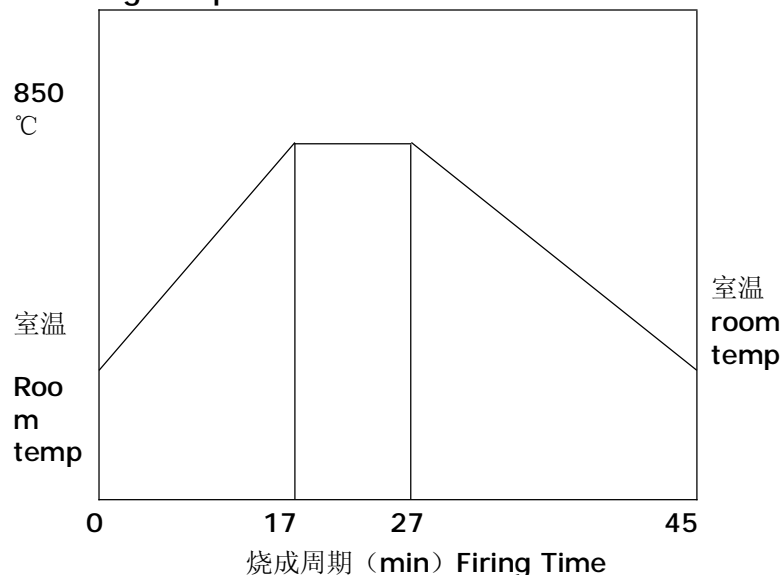
2-2. 干燥条件：150℃×3min

2-3. Drying conditions: 150℃*3 min

2-4. 烧成条件：850℃×10min

2-4, Firing conditions: 850℃*10 min

烧成温度（℃） Firing Temperature



* 以上是标准条件

The above is standard conditions

* 也可以根据用户条件略微变动

(烧成温度可变动范围: $850^{\circ}\text{C} \pm 5^{\circ}\text{C}$)

It can be slightly adjusted according to customer conditions

(Firing temperature range: $850 \pm 5^{\circ}\text{C}$)

3. 保存条件

3. Shelf life

5°C以下暗处可保存6个月,使用时请室温放置3小时左右,至浆料同室温再开启密封带,防止水分进入。

It has a shelf life of 6 months to be stored in dark place with a temperature $< 5^{\circ}\text{C}$. Before opening, it should be keep in room temperature for 3 hours, and open the seal when the temperature of silver palladium ink materials is the same as that of room, to avoid seeping of water.

4. 出厂检查报告

4. Delivery Inspection report

每批产品应附有下列数据:

- 1) 产品名称
- 2) 批号
- 3) 数量
- 4) 附着力
- 5) 方阻
- 6) 无机物含量
- 7) 粘度

Every batch product should attach the below data:

- 1) Product name
- 2) Batch number
- 3) Quantity
- 4) Adhesive force
- 5) Resistivity
- 6) Inorganic substance content
- 7) Viscosity

5. 包装

5.Packaging

P.P.容器 2000±3g/罐

P.P container 2000+/-3g/jar

6. 质量说明

6.Quality specifications

6.1 无机物含量:

6.1 Inorganic substance content

项 目 / 名 称 Item/Name	DHC-PF-8083D
无机物含量 (wt%) Inorganic substance content	82% ~86%

6.2 粘度标准: 190±20 Kcps (25℃ Brookfield HBT DV-II+ #14 10RPM)

6.2 Viscosity standard :190+/-20Kcps (25℃ Brookfield HBT DV-II+ #14 10RPM)

6.3 烧成厚度 : 10-15µm (SURFCOM 113B Model)

6.3 Fired thickness:10-15µm (SURFCOM 113B Model)

6.4 电阻率

6.4 Resistivity

标准电阻率: ≤10.0mΩ/□

Standard resistivity: ≤10.0mΩ/□

6.5 附着强度

6.5 Adhesive strength

附着力 : ≥20.0kg.f

Adhesive force: ≥20.0kg.f

附着力测试方法 : push-pull 50kgf 标准拉力计, 2mm×2mm 焊接区,
Φ0.8mm 引线,拉力测试

Test method for adhesive force: push-pull 50kgf standard force gauge, 2mm*2mm weld zone, Φ0.8mm wire lead, tensile test.

6.6 焊接条件

6.6 Soldering condition

- 1) 焊锡: Sn:Ag:Cu =96:3.5:0.5
- 1) Solder: Sn:Ag:Cu =96:3.5:0.5

- 2) 温度: 250±2℃
- 2) Temperature: 250±2℃

- 3) 浸焊时间: 5 秒 (1 次)
- 3) Solder dipping Time: 5 Sec (one time)

项目/名称 Item/Name	DHC-PF-8083D
浸焊次数 Solder dipping Time	3~5
线宽 (W/T) Trace Width	0.73mm/10um

6.7 浆料粒径: 5~7um

Ink Diameter: 5-7 um